

ABSTRACT

A silicon wafer has a plurality of integrated circuits terminated on a surface of the silicon wafer. The silicon wafer has a soluble protective coat on the surface of the silicon wafer. The coated silicon wafer may be processed by laser scribing. A solvent wash may be used to remove the soluble protective coat and debris from laser scribing. The coated silicon wafer may be saw cut after laser scribing. A flow of solvent may be provided during the saw cutting. The flow of solvent may be sufficient to remove at least a substantial portion of the soluble protective coat.